Our Materials and Services for the Entire Semicon Journey

Products | Services

Silicon Ingot → Wafer Manufacturing → Bare Wafer → Wafer Processing (Front End of Line / Back End of Line) → Processed Wafer → Packaging Process → Semiconductor Packaging

Wafer Manufacturing

Silicon Ingot
- Synthetic Quartz **Mitsubishi Synthetic Silica**

Wafer
- Functional Cleaner
- Ultra High Purity Process Chemicals
- GaN Substrate **SCAAT™**

Wafer Processing

Front End of Line

Deposition
- Precursor **Gelest, Inc.**

Lithography
- Anti-static Agent **aquaSAVE™**
- ArF & EUV Resist Polymer **Lithomax™**

CMP/Cleaning
- Ultra High Purity Process Chemicals
- Post CMP Cleaner

Back End of Line

Deposition
- Precursor **Gelest, Inc.**

Lithography
- Plastic Parts **Techtron™**

CMP/Cleaning
- CMP Retainer Ring **Mitsubishi Chemical Advanced Materials**
- Post CMP Cleaner

Packaging Process

Dicing
- Polyester Film **DIAFOIL™**/ Polyolefin Film **ARTPLY™**

Packaging
- Low Dielectric Resin/ Epoxy Resin **jER™**
- C2/C4 Bump
- Negative CTE Filler
- Thermal Conductive Sheet
- Neutron Shields

Services

- Wafer Reclaiming **Shinryo Corporation**
- Precision Cleaning **Shinryo Corporation / Cleanpart**
- Plating Services **Shinryo Corporation**
- Ultra-pure Water Production / Wastewater Treatment & Recycle **Mitsubishi Chemical Aqua Solutions Co., Ltd.**
  - Ion Exchange Resin **DIAION™**
  - MBR Membrane **STERAPORE™**
- Chemical Supply System / Chemical Recycle System **Mitsubishi Chemical Engineering Corporation**

MITSUBISHI CHEMICAL GROUP

MITSUBISHI CHEMICAL CORPORATION